Lattice Semiconductor Corporation - LFXP20E-3FN388C Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	20000
Total RAM Bits	405504
Number of I/O	268
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	388-BBGA
Supplier Device Package	388-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp20e-3fn388c

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Table 2-1. Slice Signal Descriptions

Function	Type	Signal Names	Description
Input	Data signal	A0, B0, C0, D0	Inputs to LUT4
Input	Data signal	A1, B1, C1, D1	Inputs to LUT4
Input	Multi-purpose	M0	Multipurpose Input
Input	Multi-purpose	M1	Multipurpose Input
Input	Control signal	CE	Clock Enable
Input	Control signal	LSR	Local Set/Reset
Input	Control signal	CLK	System Clock
Input	Inter-PFU signal	FCIN	Fast Carry In[1]
Output	Data signals	F0, F1	LUT4 output register bypass signals
Output	Data signals	Q0, Q1	Register Outputs
Output	Data signals	OFX0	Output of a LUT5 MUX
Output	Data signals	OFX1	Output of a LUT6, LUT7, LUT8[2] MUX depending on the slice
Output	Inter-PFU signal	FCO	For the right most PFU the fast carry chain output[1]

1. See Figure 2-2 for connection details.
2. Requires two PFUs.

Modes of Operation

Each Slice is capable of four modes of operation: Logic, Ripple, RAM and ROM. The Slice in the PFF is capable of all modes except RAM. Table 2-2 lists the modes and the capability of the Slice blocks.

Table 2-2. Slice Modes

	Logic	Ripple	RAM	ROM
PFU Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	SP 16x2	ROM 16x1 x 2
PFF Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	N/A	ROM 16x1 x 2

Logic Mode: In this mode, the LUTs in each Slice are configured as 4-input combinatorial lookup tables. A LUT4 can have 16 possible input combinations. Any logic function with four inputs can be generated by programming this lookup table. Since there are two LUT4s per Slice, a LUT5 can be constructed within one Slice. Larger lookup tables such as LUT6, LUT7 and LUT8 can be constructed by concatenating other Slices.

Ripple Mode: Ripple mode allows the efficient implementation of small arithmetic functions. In ripple mode, the following functions can be implemented by each Slice:

- Addition 2-bit
- Subtraction 2-bit
- Add/Subtract 2-bit using dynamic control
- Up counter 2-bit
- Down counter 2-bit
- Ripple mode multiplier building block
- Comparator functions of A and B inputs
  - A greater-than-or-equal-to B
  - A not-equal-to B
  - A less-than-or-equal-to B

Two additional signals: Carry Generate and Carry Propagate are generated per Slice in this mode, allowing fast arithmetic functions to be constructed by concatenating Slices.

RAM Mode: In this mode, distributed RAM can be constructed using each LUT block as a 16x1-bit memory. Through the combination of LUTs and Slices, a variety of different memories can be constructed.

in selected blocks the input to the DQS delay block. If one of the bypass options is not chosen, the signal first passes through an optional delay block. This delay, if selected, ensures no positive input-register hold-time requirement when using a global clock.

The input block allows two modes of operation. In the single data rate (SDR) the data is registered, by one of the registers in the single data rate sync register block, with the system clock. In the DDR Mode two registers are used to sample the data on the positive and negative edges of the DQS signal creating two data streams, D0 and D2. These two data streams are synchronized with the system clock before entering the core. Further discussion on this topic is in the DDR Memory section of this data sheet.

Figure 2-21 shows the input register waveforms for DDR operation and Figure 2-22 shows the design tool primitives. The SDR/SYNC registers have reset and clock enable available.

The signal DDRCLKPOL controls the polarity of the clock used in the synchronization registers. It ensures adequate timing when data is transferred from the DQS to the system clock domain. For further discussion of this topic, see the DDR memory section of this data sheet.

Figure 2-20. Input Register Diagram

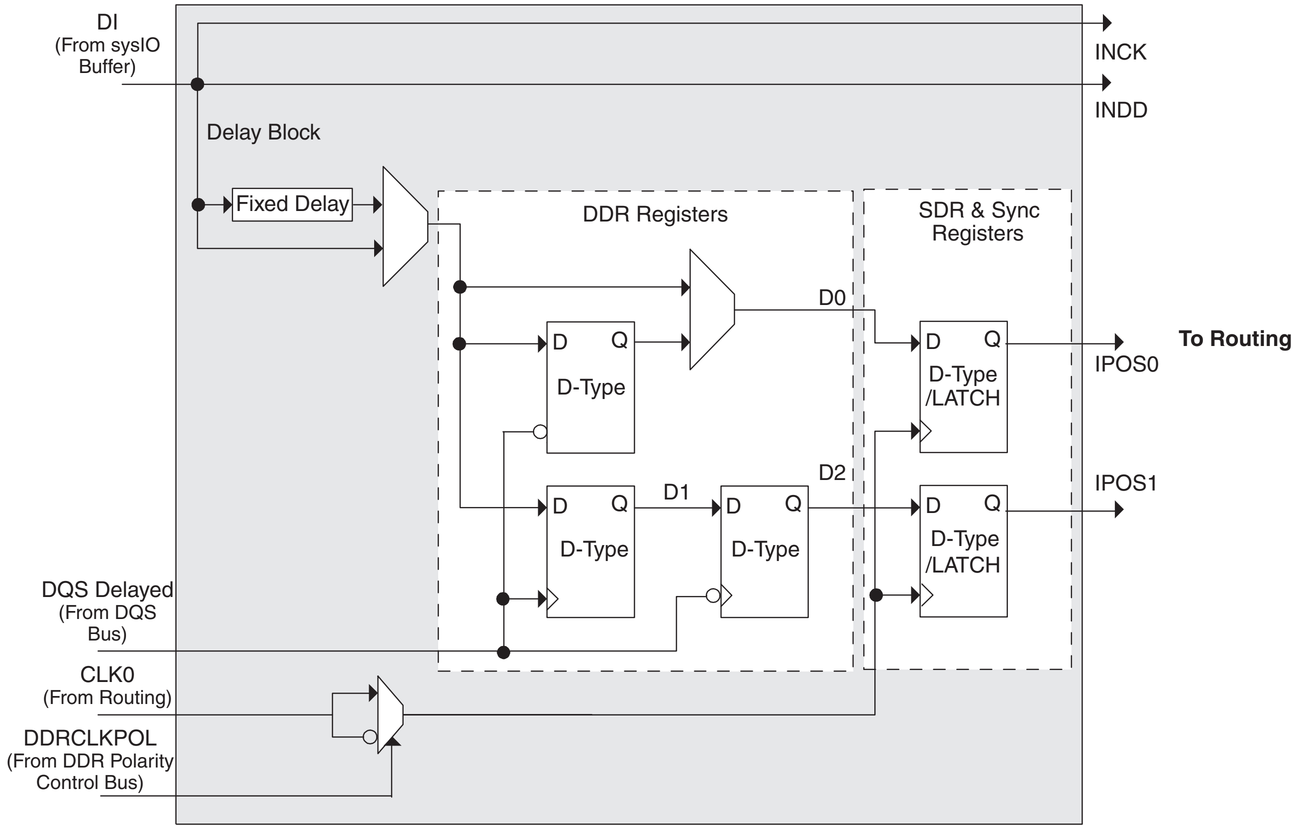


Figure 2-21. Input Register DDR Waveforms

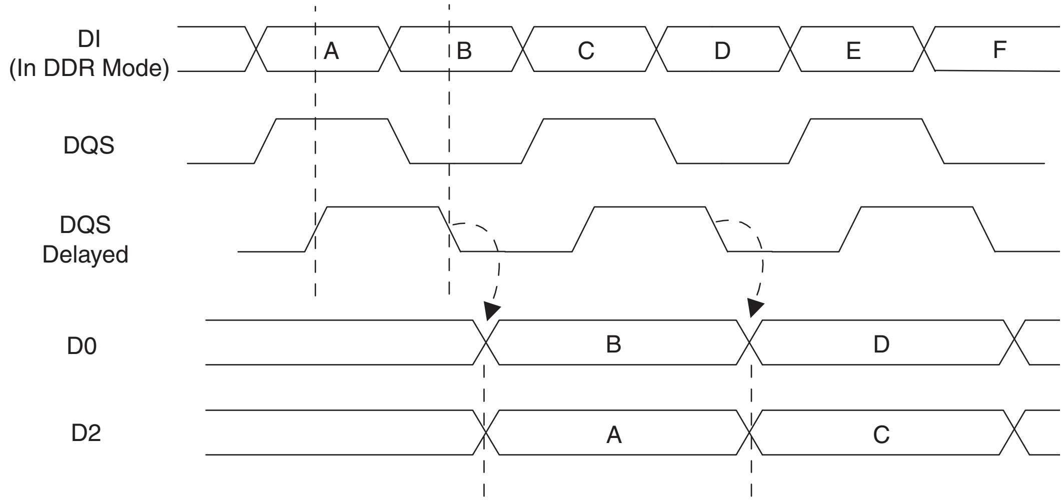
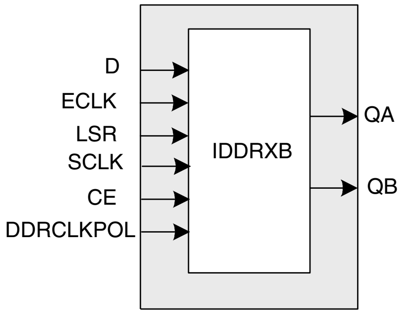


Figure 2-22. INDDRXB Primitive



Output Register Block

The output register block provides the ability to register signals from the core of the device before they are passed to the sysIO buffers. The block contains a register for SDR operation that is combined with an additional latch for DDR operation. Figure 2-23 shows the diagram of the Output Register Block.

In SDR mode, ONEG0 feeds one of the flip-flops that then feeds the output. The flip-flop can be configured as a D-type or as a latch. In DDR mode, ONEG0 is fed into one register on the positive edge of the clock and OPOS0 is latched. A multiplexer running off the same clock selects the correct register for feeding to the output (D0).

Figure 2-24 shows the design tool DDR primitives. The SDR output register has reset and clock enable available. The additional register for DDR operation does not have reset or clock enable available.

Polarity Control Logic

In a typical DDR Memory interface design, the phase relation between the incoming delayed DQS strobe and the internal system Clock (during the READ cycle) is unknown.

The LatticeXP family contains dedicated circuits to transfer data between these domains. To prevent setup and hold violations at the domain transfer between DQS (delayed) and the system Clock a clock polarity selector is used. This changes the edge on which the data is registered in the synchronizing registers in the input register block. This requires evaluation at the start of the each READ cycle for the correct clock polarity.

Prior to the READ operation in DDR memories DQS is in tristate (pulled by termination). The DDR memory device drives DQS low at the start of the preamble state. A dedicated circuit detects this transition. This signal is used to control the polarity of the clock to the synchronizing registers.

sysIO Buffer

Each I/O is associated with a flexible buffer referred to as a sysIO buffer. These buffers are arranged around the periphery of the device in eight groups referred to as Banks. The sysIO buffers allow users to implement the wide variety of standards that are found in today's systems including LVCMOS, SSTL, HSTL, LVDS and LVPECL.

sysIO Buffer Banks

LatticeXP devices have eight sysIO buffer banks; each is capable of supporting multiple I/O standards. Each sysIO bank has its own I/O supply voltage (V_{CCIO}), and two voltage references V_{REF1} and V_{REF2} resources allowing each bank to be completely independent from each other. Figure 2-28 shows the eight banks and their associated supplies.

In the LatticeXP devices, single-ended output buffers and ratioed input buffers (LVTTL, LVCMOS, PCI and PCI-X) are powered using V_{CCIO}. LVTTL, LVCMOS33, LVCMOS25 and LVCMOS12 can also be set as a fixed threshold input independent of $V_{CCIO.}$ In addition to the bank V_{CCIO} supplies, the LatticeXP devices have a V_{CC} core logic power supply, and a V_{CCAUX} supply that power all differential and referenced buffers.

Each bank can support up to two separate VREF voltages, VREF1 and VREF2 that set the threshold for the referenced input buffers. In the LatticeXP devices, a dedicated pin in a bank can be configured to be a reference voltage supply pin. Each I/O is individually configurable based on the bank's supply and reference voltages.

Lattice Semiconductor Corporation

LatticeXP Family Data Sheet DC and Switching Characteristics

November 2007 Data Sheet DS1001

Absolute Maximum Ratings[1, 2, 3, 4]

	XPE (1.2V)	XPC (1.8V/2.5V/3.3V)
Supply Voltage V_{CC}	-0.5 to 1.32V	-0.5 to 3.75V
Supply Voltage V_{CCP}	-0.5 to 1.32V	-0.5 to 3.75V
Supply Voltage V_{CCAUX}	-0.5 to 3.75V	-0.5 to 3.75V
Supply Voltage V_{CCJ}	-0.5 to 3.75V	-0.5 to 3.75V
Output Supply Voltage V_{CCIO}	-0.5 to 3.75V	-0.5 to 3.75V
I/O Tristate Voltage Applied[5]	-0.5 to 3.75V	-0.5 to 3.75V
Dedicated Input Voltage Applied [5]	-0.5 to 3.75V	-0.5 to 4.25V
Storage Temperature (Ambient)	-65 to 150°C	-65 to 150°C
Junction Temp. (Tj)	+125°C	+125°C

1. Stress above those listed under the “Absolute Maximum Ratings” may cause permanent damage to the device. Functional operation of the device at these or any other conditions outside of those indicated in the operational sections of this specification is not implied.
2. Compliance with the Lattice *Thermal Management* document is required.
3. All voltages referenced to GND.
4. All chip grounds are connected together to a common package GND plane.
5. Overshoot and undershoot of -2V to (V_{IHMAX} + 2) volts is permitted for a duration of <20ns.

Recommended Operating Conditions[3]

Symbol	Parameter	Min.	Max.	Units
V_{CC}	Core Supply Voltage for 1.2V Devices	1.14	1.26	V
	Core Supply Voltage for 1.8V/2.5V/3.3V Devices	1.71	3.465	V
V_{CCP}	Supply Voltage for PLL for 1.2V Devices	1.14	1.26	V
	Supply Voltage for PLL for 1.8V/2.5V/3.3V Devices	1.71	3.465	V
V_{CCAUX}[4]	Auxiliary Supply Voltage	3.135	3.465	V
V_{CCIO}[1, 2]	I/O Driver Supply Voltage	1.14	3.465	V
V_{CCJ}[1]	Supply Voltage for IEEE 1149.1 Test Access Port	1.14	3.465	V
t_{JCOM}	Junction Temperature, Commercial Operation	0	85	C
t_{JIND}	Junction Temperature, Industrial Operation	-40	100	C
$t_{JFLASHCOM}$	Junction Temperature, Flash Programming, Commercial	0	85	C
$t_{JFLASHIND}$	Junction Temperature, Flash Programming, Industrial	0	85	C

1. If V_{CCIO} or V_{CCJ} is set to 3.3V, they must be connected to the same power supply as $V_{CCAUX.}$ For the XPE devices (1.2V V_{CC}), if V_{CCIO} or V_{CCJ} is set to 1.2V, they must be connected to the same power supply as V_{CC}.
2. See recommended voltages by I/O standard in subsequent table.
3. The system designer must ensure that the FPGA design stays within the specified junction temperature and package thermal capabilities of the device based on the expected operating frequency, activity factor and environment conditions of the system.
4. V_{CCAUX} ramp rate must not exceed 30mV/µs during power up when transitioning between 0V and 3.3V.

sysIO Single-Ended DC Electrical Characteristics

Input/Output Standard	V_{IL}		V_{IH}		V_{OL} Max. (V)	V_{OH} Min. (V)	I_{OL} (mA)	I_{OH} (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVCMOS 3.3	-0.3	0.8	2.0	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVTTL	-0.3	0.8	2.0	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 2.5	-0.3	0.7	1.7	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.8	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	V_{CCIO} - 0.4	16, 12, 8, 4	-16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.5	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	V_{CCIO} - 0.4	8, 4	-8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.2 ("C" Version)	-0.3	0.42	0.78	3.6	0.4	V_{CCIO} - 0.4	6, 2	-6, -2
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.2 ("E" Version)	-0.3	$0.35V_{CC}$	$0.65V_{CC}$	3.6	0.4	V_{CCIO} - 0.4	6, 2	-6, -2
					0.2	V_{CCIO} - 0.2	0.1	-0.1
PCI	-0.3	$0.3V_{CCIO}$	$0.5V_{CCIO}$	3.6	$0.1V_{CCIO}$	$0.9V_{CCIO}$	1.5	-0.5
SSTL3 class I	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.7	V_{CCIO} - 1.1	8	-8
SSTL3 class II	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.5	V_{CCIO} - 0.9	16	-16
SSTL2 class I	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.54	V_{CCIO} - 0.62	7.6	-7.6
SSTL2 class II	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.35	V_{CCIO} - 0.43	15.2	-15.2
SSTL18 class I	-0.3	V_{REF} - 0.125	V_{REF} + 0.125	3.6	0.4	V_{CCIO} - 0.4	6.7	-6.7
HSTL15 class I	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	8	-8
HSTL15 class III	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	24	-8
HSTL18 class I	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	9.6	-9.6
HSTL18 class II	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	16	-16
HSTL18 class III	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	24	-8

1. The average DC current drawn by I/Os between GND connections, or between the last GND in an I/O bank and the end of an I/O bank, as shown in the logic signal connections table shall not exceed n * 8mA. Where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.

LatticeXP External Switching Characteristics

Over Recommended Operating Conditions

			-5		-4		-3		
Parameter	**Description**	**Device**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
General I/O Pin Parameters (Using Primary Clock without PLL)[1]									
t_{CO}	Clock to Output - PIO Output Register	LFXP3	—	5.12	—	6.12	—	7.43	ns
		LFXP6	—	5.30	—	6.34	—	7.69	ns
		LFXP10	—	5.52	—	6.60	—	8.00	ns
		LFXP15	—	5.72	—	6.84	—	8.29	ns
		LFXP20	—	5.97	—	7.14	—	8.65	ns
t_{SU}	Clock to Data Setup - PIO Input Register	LFXP3	-0.40	—	-0.28	—	-0.16	—	ns
		LFXP6	-0.33	—	-0.32	—	-0.30	—	ns
		LFXP10	-0.61	—	-0.71	—	-0.81	—	ns
		LFXP15	-0.71	—	-0.77	—	-0.87	—	ns
		LFXP20	-0.95	—	-1.14	—	-1.35	—	ns
t_{H}	Clock to Data Hold - PIO Input Register	LFXP3	2.10	—	2.50	—	2.98	—	ns
		LFXP6	2.28	—	2.72	—	3.24	—	ns
		LFXP10	3.02	—	3.51	—	3.71	—	ns
		LFXP15	2.70	—	3.22	—	3.85	—	ns
		LFXP20	2.95	—	3.52	—	4.21	—	ns
t_{SU_DEL}	Clock to Data Setup - PIO Input Register with Input Data Delay	LFXP3	2.38	—	2.49	—	2.66	—	ns
		LFXP6	2.92	—	3.18	—	3.42	—	ns
		LFXP10	2.72	—	2.75	—	2.84	—	ns
		LFXP15	2.99	—	3.13	—	3.18	—	ns
		LFXP20	4.47	—	4.56	—	4.80	—	ns
t_{H_DEL}	Clock to Data Hold - PIO Input Register with Input Data Delay	LFXP3	-0.70	—	-0.80	—	-0.92	—	ns
		LFXP6	-0.47	—	-0.38	—	-0.31	—	ns
		LFXP10	-0.60	—	-0.47	—	-0.32	—	ns
		LFXP15	-1.05	—	-0.98	—	-1.01	—	ns
		LFXP20	-0.80	—	-0.58	—	-0.31	—	ns
f_{MAX_IO}	Clock Frequency of I/O and PFU Register	All	—	400	—	360	—	320	MHz
DDR I/O Pin Parameters[2]									
t_{DVADQ}	Data Valid After DQS (DDR Read)	All	—	0.19	—	0.19	—	0.19	UI
t_{DVEDQ}	Data Hold After DQS (DDR Read)	All	0.67	—	0.67	—	0.67	—	UI
t_{DQVBS}	Data Valid Before DQS	All	0.20	—	0.20	—	0.20	—	UI
t_{DQVAS}	Data Valid After DQS	All	0.20	—	0.20	—	0.20	—	UI
f_{MAX_DDR}	DDR Clock Frequency	All	95	166	95	133	95	100	MHz
Primary and Secondary Clocks									
f_{MAX_PRI}	Frequency for Primary Clock Tree	All	—	450	—	412	—	375	MHz
t_{W_PRI}	Clock Pulse Width for Primary Clock	All	1.19	—	1.19	—	1.19	—	ns
t_{SKEW_PRI}	Primary Clock Skew within an I/O Bank	LFXP3/6/10/15	—	250	—	300	—	350	ps
		LFXP20	—	300	—	350	—	400	ps

1. General timing numbers based on LVCMOS 2.5, 12mA.
2. DDR timing numbers based on SSTL I/O.

Timing v.F0.11

LatticeXP Internal Timing Parameters[1] (Continued)

Over Recommended Operating Conditions

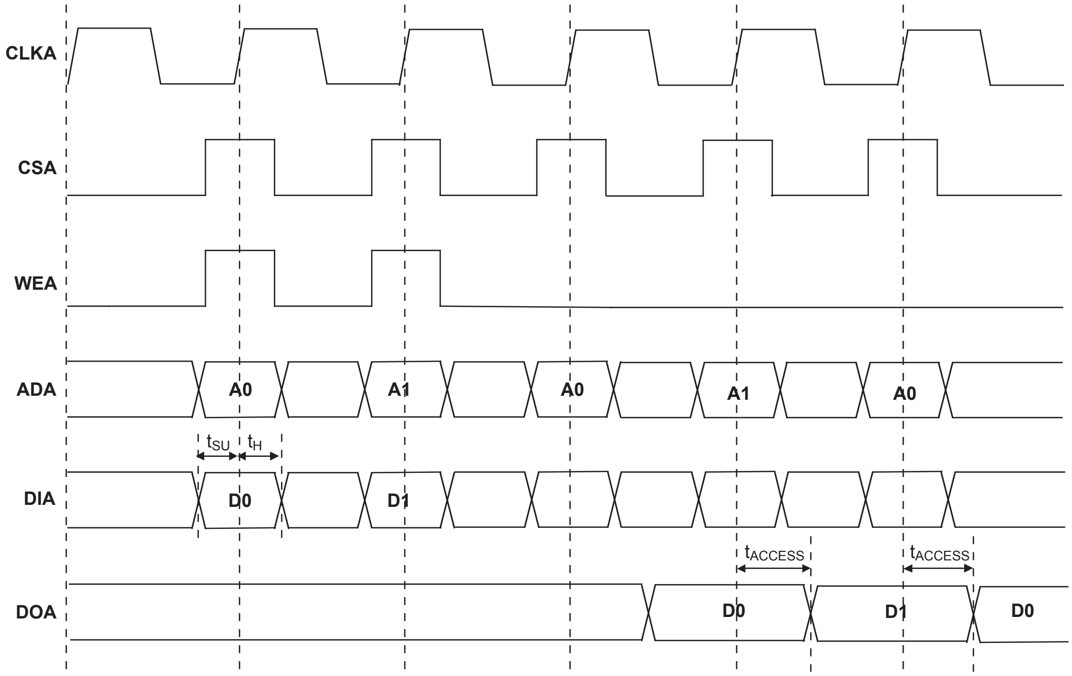
Parameter	Description	-5		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t_{RSTO_EBR}	Reset To Output Delay Time from EBR Output Register	—	1.61	—	1.94	—	2.32	ns
PLL Parameters								
t_{RSTREC}	Reset Recovery to Rising Clock	1.00	—	1.00	—	1.00	—	ns
t_{RSTSU}	Reset Signal Setup Time	1.00	—	1.00	—	1.00	—	ns

1. Internal parameters are characterized but not tested on every device.

Timing v.F0.11

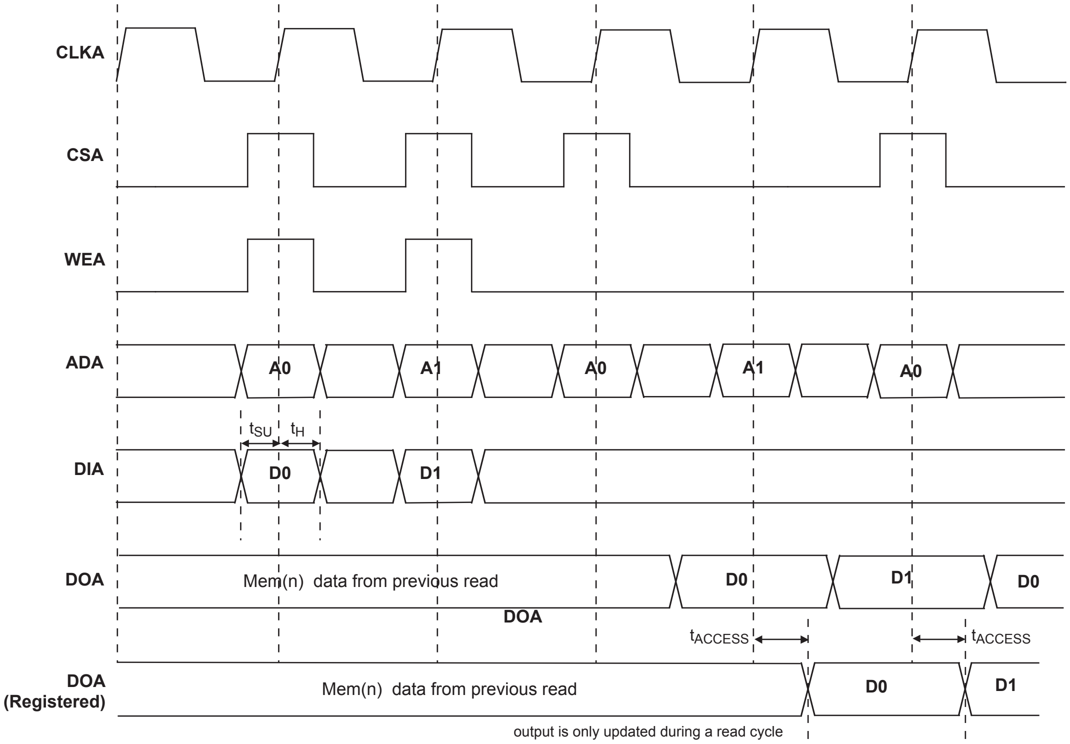
EBR Memory Timing Diagrams

Figure 3-8. Read Mode (Normal)



Note: Input data and address are registered at the positive edge of the clock and output data appears after the positive of the clock.

Figure 3-9. Read Mode with Input and Output Registers



LFXP3 Logic Signal Connections: 100 TQFP (Cont.)

Pin Number	Pin Function	Bank	Differential	Dual Function
88	PT14B	1	-	D7
89	PT13B	0	C	BUSY
90	GNDIO0	0	-	-
91	PT13A	0	T	CS1N
92	PT12B	0	C	PCLKC0_0
93	PT12A	0	T	PCLKT0_0
94	VCCIO0	0	-	-
95	PT9A	0	-	DOUT
96	PT8A	0	-	WRITEN
97	PT6A	0	-	DI
98	PT5A	0	-	CSN
99	GND	-	-	-
100	CFG0	0	-	-

1. Applies to LFXP “C” only.
2. Applies to LFXP “E” only.
3. Supports dedicated LVDS outputs.

LFXP3 & LFXP6 Logic Signal Connections: 144 TQFP (Cont.)

Pin Number	LFXP3				LFXP6			
	Pin Function	Bank	Differential	Dual Function	Pin Function	Bank	Differential	Dual Function
47	PB11A	5	T	DQS	PB14A	5	T	DQS
48	PB11B	5	C	-	PB14B	5	C	-
49	VCCIO5	5	-	-	VCCIO5	5	-	-
50	PB12A	5	T	-	PB15A	5	T	-
51	PB12B	5	C	-	PB15B	5	C	-
52	PB13A	5	T	-	PB16A	5	T	-
53	PB13B	5	C	-	PB16B	5	C	-
54	GND	-	-	-	GND	-	-	-
55	PB14A	4	T	-	PB17A	4	T	-
56	GNDIO4	4	-	-	GNDIO4	4	-	-
57	PB14B	4	C	-	PB17B	4	C	-
58	PB15A	4	T	PCLKT4_0	PB18A	4	T	PCLKT4_0
59	PB15B	4	C	PCLKC4_0	PB18B	4	C	PCLKC4_0
60	PB16A	4	T	-	PB19A	4	T	-
61	VCCIO4	4	-	-	VCCIO4	4	-	-
62	PB16B	4	C	-	PB19B	4	C	-
63	PB19A	4	T	DQS	PB22A	4	T	DQS
64	GNDIO4	4	-	-	GNDIO4	4	-	-
65	PB19B	4	C	VREF1_4	PB22B	4	C	VREF1_4
66	PB20A	4	T	-	PB23A	4	T	-
67	PB20B	4	C	-	PB23B	4	C	-
68	VCCIO4	4	-	-	VCCIO4	4	-	-
69	PB22A	4	-	-	PB25A	4	-	-
70	PB24A	4	T	VREF2_4	PB27A	4	T	VREF2_4
71	PB24B	4	C	-	PB27B	4	C	-
72	PB25A	4	-	-	PB28A	4	-	-
73	VCC	-	-	-	VCC	-	-	-
74	PR18B	3	C[3]	-	PR26B	3	C[3]	-
75	GNDIO3	3	-	-	GNDIO3	3	-	-
76	PR18A	3	T[3]	-	PR26A	3	T[3]	-
77	PR17B	3	C	-	PR25B	3	C	-
78	PR17A	3	T	-	PR25A	3	T	-
79	PR16B	3	C[3]	-	PR24B	3	C[3]	-
80	PR16A	3	T[3]	DQS	PR24A	3	T[3]	DQS
81	PR15B	3	-	VREF1_3	PR23B	3	-	VREF1_3
82	PR14A	3	-	VREF2_3	PR22A	3	-	VREF2_3
83	PR13B	3	C	-	PR21B	3	C[3]	-
84	PR13A	3	T	-	PR21A	3	T[3]	-
85	GND	-	-	-	GND	-	-	-
86	PR12A	3	-	-	PR20A	3	-	-
87	PR11B	3	C	-	PR19B	3	C[3]	-
88	VCCIO3	3	-	-	VCCIO3	3	-	-
89	PR11A	3	T	-	PR19A	3	T[3]	-
90	GNDP1	-	-	-	GNDP1	-	-	-
91	VCCP1	-	-	-	VCCP1	-	-	-
92	PR9B	2	C	PCLKC2_0	PR12B	2	C	PCLKC2_0

LFXP3 & LFXP6 Logic Signal Connections: 208 PQFP (Cont.)

Pin Number	LFXP3				LFXP6			
	Pin Function	Bank	Differential	Dual Function	Pin Function	Bank	Differential	Dual Function
185	PT13A	0	T	CS1N	PT16A	0	T	CS1N
186	PT12B	0	C	PCLKC0_0	PT15B	0	C	PCLKC0_0
187	PT12A	0	T	PCLKT0_0	PT15A	0	T	PCLKT0_0
188	PT11B	0	C	-	PT14B	0	C	-
189	VCCIO0	0	-	-	VCCIO0	0	-	-
190	PT11A	0	T	DQS	PT14A	0	T	DQS
191	PT10B	0	-	-	PT13B	0	-	-
192	PT9A	0	-	DOUT	PT12A	0	-	DOUT
193	PT8B	0	C	-	PT11B	0	C	-
194	GNDIO0	0	-	-	GNDIO0	0	-	-
195	PT8A	0	T	WRITEN	PT11A	0	T	WRITEN
196	PT7B	0	C	-	PT10B	0	C	-
197	PT7A	0	T	VREF1_0	PT10A	0	T	VREF1_0
198	PT6B	0	C	-	PT9B	0	C	-
199	VCCIO0	0	-	-	VCCIO0	0	-	-
200	PT6A	0	T	DI	PT9A	0	T	DI
201	PT5B	0	C	-	PT8B	0	C	-
202	PT5A	0	T	CSN	PT8A	0	T	CSN
203	PT4B	0	C	-	PT7B	0	C	-
204	PT4A	0	T	-	PT7A	0	T	-
205	PT3B	0	-	VREF2_0	PT6B	0	-	VREF2_0
206	PT2B	0	-	-	PT5B	0	-	-
207	GND	-	-	-	GND	-	-	-
208	CFG0	0	-	-	CFG0	0	-	-

1. Applies to LFXP “C” only.
2. Applies to LFXP “E” only.
3. Supports dedicated LVDS outputs.

LFXP6 & LFXP10 Logic Signal Connections: 256 fpBGA (Cont.)

	LFXP6				LFXP10			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
K10	GND	-	-	-	GND	-	-	-
K7	GND	-	-	-	GND	-	-	-
K8	GND	-	-	-	GND	-	-	-
K9	GND	-	-	-	GND	-	-	-
L11	GND	-	-	-	GND	-	-	-
L6	GND	-	-	-	GND	-	-	-
T1	GND	-	-	-	GND	-	-	-
T16	GND	-	-	-	GND	-	-	-
D13	VCC	-	-	-	VCC	-	-	-
D4	VCC	-	-	-	VCC	-	-	-
E12	VCC	-	-	-	VCC	-	-	-
E5	VCC	-	-	-	VCC	-	-	-
M12	VCC	-	-	-	VCC	-	-	-
M5	VCC	-	-	-	VCC	-	-	-
N13	VCC	-	-	-	VCC	-	-	-
N4	VCC	-	-	-	VCC	-	-	-
E13	VCCAUX	-	-	-	VCCAUX	-	-	-
E4	VCCAUX	-	-	-	VCCAUX	-	-	-
M13	VCCAUX	-	-	-	VCCAUX	-	-	-
M4	VCCAUX	-	-	-	VCCAUX	-	-	-
F7	VCCIO0	0	-	-	VCCIO0	0	-	-
F8	VCCIO0	0	-	-	VCCIO0	0	-	-
F10	VCCIO1	1	-	-	VCCIO1	1	-	-
F9	VCCIO1	1	-	-	VCCIO1	1	-	-
G11	VCCIO2	2	-	-	VCCIO2	2	-	-
H11	VCCIO2	2	-	-	VCCIO2	2	-	-
J11	VCCIO3	3	-	-	VCCIO3	3	-	-
K11	VCCIO3	3	-	-	VCCIO3	3	-	-
L10	VCCIO4	4	-	-	VCCIO4	4	-	-
L9	VCCIO4	4	-	-	VCCIO4	4	-	-
L7	VCCIO5	5	-	-	VCCIO5	5	-	-
L8	VCCIO5	5	-	-	VCCIO5	5	-	-
J6	VCCIO6	6	-	-	VCCIO6	6	-	-
K6	VCCIO6	6	-	-	VCCIO6	6	-	-
G6	VCCIO7	7	-	-	VCCIO7	7	-	-
H6	VCCIO7	7	-	-	VCCIO7	7	-	-

1. Applies to LFXP “C” only.
2. Applies to LFXP “E” only.
3. Supports dedicated LVDS outputs.

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
G10	GND	-	-	-	GND	-	-	-
G7	GND	-	-	-	GND	-	-	-
G8	GND	-	-	-	GND	-	-	-
G9	GND	-	-	-	GND	-	-	-
H10	GND	-	-	-	GND	-	-	-
H7	GND	-	-	-	GND	-	-	-
H8	GND	-	-	-	GND	-	-	-
H9	GND	-	-	-	GND	-	-	-
J10	GND	-	-	-	GND	-	-	-
J7	GND	-	-	-	GND	-	-	-
J8	GND	-	-	-	GND	-	-	-
J9	GND	-	-	-	GND	-	-	-
K10	GND	-	-	-	GND	-	-	-
K7	GND	-	-	-	GND	-	-	-
K8	GND	-	-	-	GND	-	-	-
K9	GND	-	-	-	GND	-	-	-
L11	GND	-	-	-	GND	-	-	-
L6	GND	-	-	-	GND	-	-	-
T1	GND	-	-	-	GND	-	-	-
T16	GND	-	-	-	GND	-	-	-
D13	VCC	-	-	-	VCC	-	-	-
D4	VCC	-	-	-	VCC	-	-	-
E12	VCC	-	-	-	VCC	-	-	-
E5	VCC	-	-	-	VCC	-	-	-
M12	VCC	-	-	-	VCC	-	-	-
M5	VCC	-	-	-	VCC	-	-	-
N13	VCC	-	-	-	VCC	-	-	-
N4	VCC	-	-	-	VCC	-	-	-
E13	VCCAUX	-	-	-	VCCAUX	-	-	-
E4	VCCAUX	-	-	-	VCCAUX	-	-	-
M13	VCCAUX	-	-	-	VCCAUX	-	-	-
M4	VCCAUX	-	-	-	VCCAUX	-	-	-
F7	VCCIO0	0	-	-	VCCIO0	0	-	-
F8	VCCIO0	0	-	-	VCCIO0	0	-	-
F10	VCCIO1	1	-	-	VCCIO1	1	-	-
F9	VCCIO1	1	-	-	VCCIO1	1	-	-
G11	VCCIO2	2	-	-	VCCIO2	2	-	-
H11	VCCIO2	2	-	-	VCCIO2	2	-	-
J11	VCCIO3	3	-	-	VCCIO3	3	-	-
K11	VCCIO3	3	-	-	VCCIO3	3	-	-
L10	VCCIO4	4	-	-	VCCIO4	4	-	-
L9	VCCIO4	4	-	-	VCCIO4	4	-	-

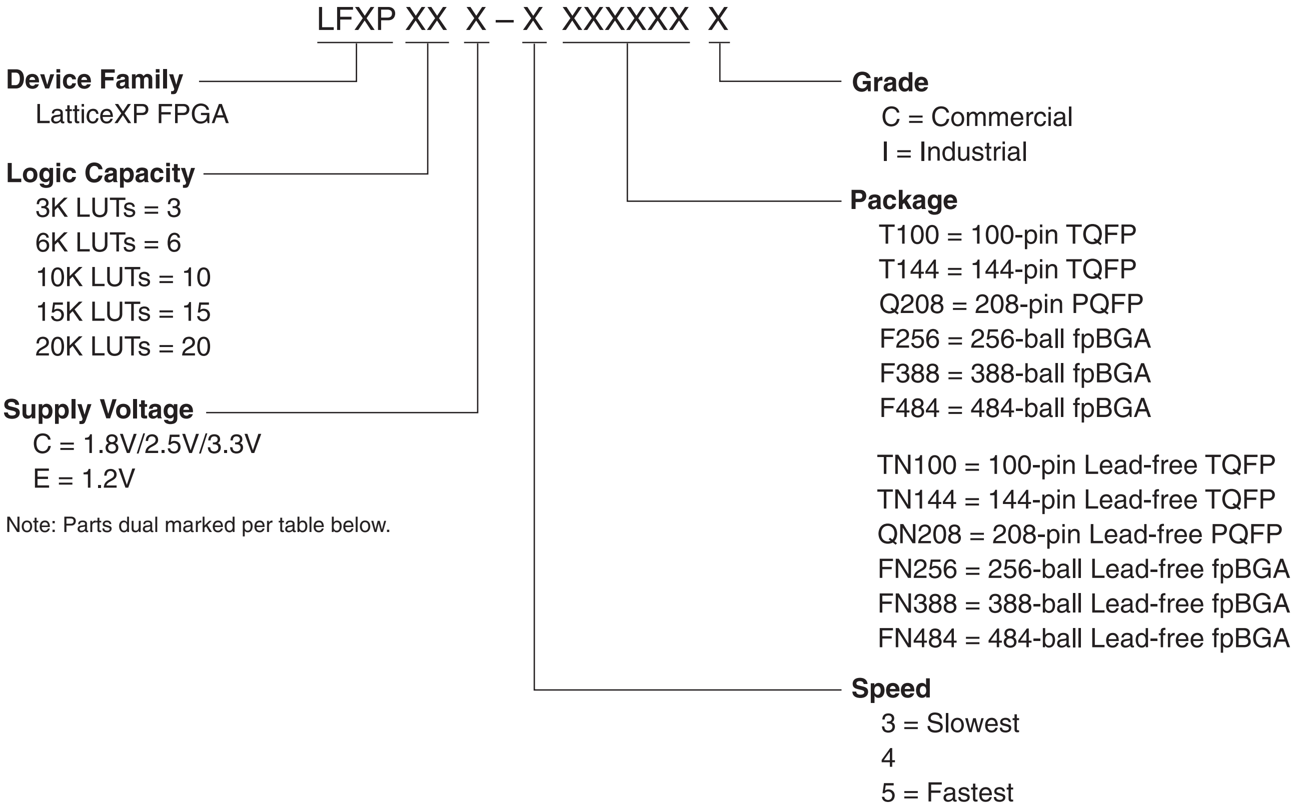
LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	**Ball Function**	**Bank**	**Differential**	**Dual Function**	**Ball Function**	**Bank**	**Differential**	**Dual Function**
J21	PR20B	2	C[3]	-	PR20B	2	C[3]	-
J22	PR20A	2	T[3]	DQS	PR20A	2	T[3]	DQS
K18	PR19B	2	-	-	PR19B	2	-	-
K19	PR18A	2	-	VREF1_2	PR18A	2	-	VREF1_2
-	GNDIO2	2	-	-	GNDIO2	2	-	-
K21	PR17B	2	C[3]	-	PR17B	2	C[3]	-
K20	PR17A	2	T[3]	-	PR17A	2	T[3]	-
H21	PR16B	2	C	RUM0_PLLC_IN_A	PR16B	2	C	RUM0_PLLC_IN_A
H22	PR16A	2	T	RUM0_PLLT_IN_A	PR16A	2	T	RUM0_PLLT_IN_A
J20	PR15B	2	C[3]	-	PR15B	2	C[3]	-
J19	PR15A	2	T[3]	-	PR15A	2	T[3]	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
J17	PR13B	2	C[3]	-	PR13B	2	C[3]	-
J18	PR13A	2	T[3]	-	PR13A	2	T[3]	-
G21	PR12B	2	C	-	PR12B	2	C	-
G22	PR12A	2	T	-	PR12A	2	T	-
F21	PR11B	2	C[3]	-	PR11B	2	C[3]	-
F22	PR11A	2	T[3]	DQS	PR11A	2	T[3]	DQS
-	GNDIO2	2	-	-	GNDIO2	2	-	-
H20	PR10B	2	-	-	PR10B	2	-	-
H19	PR9A	2	-	VREF2_2	PR9A	2	-	VREF2_2
H17	PR8B	2	C[3]	-	PR8B	2	C[3]	-
H18	PR8A	2	T[3]	-	PR8A	2	T[3]	-
E21	PR7B	2	C	RUM0_PLLC_FB_A	PR7B	2	C	RUM0_PLLC_FB_A
E22	PR7A	2	T	RUM0_PLLT_FB_A	PR7A	2	T	RUM0_PLLT_FB_A
D21	PR6B	2	C[3]	-	PR6B	2	C[3]	-
D22	PR6A	2	T[3]	-	PR6A	2	T[3]	-
G20	PR5B	2	C[3]	-	PR5B	2	C[3]	-
G19	PR5A	2	T[3]	-	PR5A	2	T[3]	-
G17	PR4B	2	C	-	PR4B	2	C	-
G18	PR4A	2	T	-	PR4A	2	T	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
F18	PR3B	2	C[3]	-	PR3B	2	C[3]	-
F19	PR3A	2	T[3]	-	PR3A	2	T[3]	-
C22	PR2B	2	-	-	PR2B	2	-	-
F20	TDO	-	-	-	TDO	-	-	-
E20	VCCJ	-	-	-	VCCJ	-	-	-
D19	TDI	-	-	-	TDI	-	-	-
E19	TMS	-	-	-	TMS	-	-	-
D20	TCK	-	-	-	TCK	-	-	-
C20	-	-	-	-	PT56A	1	-	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-

LatticeXP Family Data Sheet Ordering Information

December 2005 **Data Sheet DS1001**

Part Number Description



LFXP XX X – X XXXXXX X

Device Family
LatticeXP FPGA

Logic Capacity
3K LUTs = 3
6K LUTs = 6
10K LUTs = 10
15K LUTs = 15
20K LUTs = 20

Supply Voltage
C = 1.8V/2.5V/3.3V
E = 1.2V

Note: Parts dual marked per table below.

Grade
C = Commercial
I = Industrial

Package
T100 = 100-pin TQFP
T144 = 144-pin TQFP
Q208 = 208-pin PQFP
F256 = 256-ball fpBGA
F388 = 388-ball fpBGA
F484 = 484-ball fpBGA

TN100 = 100-pin Lead-free TQFP
TN144 = 144-pin Lead-free TQFP
QN208 = 208-pin Lead-free PQFP
FN256 = 256-ball Lead-free fpBGA
FN388 = 388-ball Lead-free fpBGA
FN484 = 484-ball Lead-free fpBGA

Speed
3 = Slowest
4
5 = Fastest

Ordering Information (Contact Factory for Specific Device Availability)

Note:þLatticeXP devices are dual marked. For example, the commercial speed grade LFXP10E-4F256C is also marked with industrial grade -3I (LFXP10E-3F256I). The commercial grade is one speed grade faster than the associated dual mark industrial grade. The slowest commercial speed grade does not have industrial markings. The markings appear as follows:

LFXP10E-
4F256C-3I

Datecode

Industrial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15E-3F484I	300	1.2V	-3	fpBGA	484	IND	15.5K
LFXP15E-4F484I	300	1.2V	-4	fpBGA	484	IND	15.5K
LFXP15E-3F388I	268	1.2V	-3	fpBGA	388	IND	15.5K
LFXP15E-4F388I	268	1.2V	-4	fpBGA	388	IND	15.5K
LFXP15E-3F256I	188	1.2V	-3	fpBGA	256	IND	15.5K
LFXP15E-4F256I	188	1.2V	-4	fpBGA	256	IND	15.5K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20E-3F484I	340	1.2V	-3	fpBGA	484	IND	19.7K
LFXP20E-4F484I	340	1.2V	-4	fpBGA	484	IND	19.7K
LFXP20E-3F388I	268	1.2V	-3	fpBGA	388	IND	19.7K
LFXP20E-4F388I	268	1.2V	-4	fpBGA	388	IND	19.7K
LFXP20E-3F256I	188	1.2V	-3	fpBGA	256	IND	19.7K
LFXP20E-4F256I	188	1.2V	-4	fpBGA	256	IND	19.7K

Commercial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20C-3FN484C	340	1.8/2.5/3.3V	-3	fpBGA	484	COM	19.7K
LFXP20C-4FN484C	340	1.8/2.5/3.3V	-4	fpBGA	484	COM	19.7K
LFXP20C-5FN484C	340	1.8/2.5/3.3V	-5	fpBGA	484	COM	19.7K
LFXP20C-3FN388C	268	1.8/2.5/3.3V	-3	fpBGA	388	COM	19.7K
LFXP20C-4FN388C	268	1.8/2.5/3.3V	-4	fpBGA	388	COM	19.7K
LFXP20C-5FN388C	268	1.8/2.5/3.3V	-5	fpBGA	388	COM	19.7K
LFXP20C-3FN256C	188	1.8/2.5/3.3V	-3	fpBGA	256	COM	19.7K
LFXP20C-4FN256C	188	1.8/2.5/3.3V	-4	fpBGA	256	COM	19.7K
LFXP20C-5FN256C	188	1.8/2.5/3.3V	-5	fpBGA	256	COM	19.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3E-3QN208C	136	1.2V	-3	PQFP	208	COM	3.1K
LFXP3E-4QN208C	136	1.2V	-4	PQFP	208	COM	3.1K
LFXP3E-5QN208C	136	1.2V	-5	PQFP	208	COM	3.1K
LFXP3E-3TN144C	100	1.2V	-3	TQFP	144	COM	3.1K
LFXP3E-4TN144C	100	1.2V	-4	TQFP	144	COM	3.1K
LFXP3E-5TN144C	100	1.2V	-5	TQFP	144	COM	3.1K
LFXP3E-3TN100C	62	1.2V	-3	TQFP	100	COM	3.1K
LFXP3E-4TN100C	62	1.2V	-4	TQFP	100	COM	3.1K
LFXP3E-5TN100C	62	1.2V	-5	TQFP	100	COM	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6E-3FN256C	188	1.2V	-3	fpBGA	256	COM	5.8K
LFXP6E-4FN256C	188	1.2V	-4	fpBGA	256	COM	5.8K
LFXP6E-5FN256C	188	1.2V	-5	fpBGA	256	COM	5.8K
LFXP6E-3QN208C	142	1.2V	-3	PQFP	208	COM	5.8K
LFXP6E-4QN208C	142	1.2V	-4	PQFP	208	COM	5.8K
LFXP6E-5QN208C	142	1.2V	-5	PQFP	208	COM	5.8K
LFXP6E-3TN144C	100	1.2V	-3	TQFP	144	COM	5.8K
LFXP6E-4TN144C	100	1.2V	-4	TQFP	144	COM	5.8K
LFXP6E-5TN144C	100	1.2V	-5	TQFP	144	COM	5.8K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10E-3FN388C	244	1.2V	-3	fpBGA	388	COM	9.7K
LFXP10E-4FN388C	244	1.2V	-4	fpBGA	388	COM	9.7K
LFXP10E-5FN388C	244	1.2V	-5	fpBGA	388	COM	9.7K
LFXP10E-3FN256C	188	1.2V	-3	fpBGA	256	COM	9.7K
LFXP10E-4FN256C	188	1.2V	-4	fpBGA	256	COM	9.7K
LFXP10E-5FN256C	188	1.2V	-5	fpBGA	256	COM	9.7K

Commercial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15E-3FN484C	300	1.2V	-3	fpBGA	484	COM	15.5K
LFXP15E-4FN484C	300	1.2V	-4	fpBGA	484	COM	15.5K
LFXP15E-5FN484C	300	1.2V	-5	fpBGA	484	COM	15.5K
LFXP15E-3FN388C	268	1.2V	-3	fpBGA	388	COM	15.5K
LFXP15E-4FN388C	268	1.2V	-4	fpBGA	388	COM	15.5K
LFXP15E-5FN388C	268	1.2V	-5	fpBGA	388	COM	15.5K
LFXP15E-3FN256C	188	1.2V	-3	fpBGA	256	COM	15.5K
LFXP15E-4FN256C	188	1.2V	-4	fpBGA	256	COM	15.5K
LFXP15E-5FN256C	188	1.2V	-5	fpBGA	256	COM	15.5K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20E-3FN484C	340	1.2V	-3	fpBGA	484	COM	19.7K
LFXP20E-4FN484C	340	1.2V	-4	fpBGA	484	COM	19.7K
LFXP20E-5FN484C	340	1.2V	-5	fpBGA	484	COM	19.7K
LFXP20E-3FN388C	268	1.2V	-3	fpBGA	388	COM	19.7K
LFXP20E-4FN388C	268	1.2V	-4	fpBGA	388	COM	19.7K
LFXP20E-5FN388C	268	1.2V	-5	fpBGA	388	COM	19.7K
LFXP20E-3FN256C	188	1.2V	-3	fpBGA	256	COM	19.7K
LFXP20E-4FN256C	188	1.2V	-4	fpBGA	256	COM	19.7K
LFXP20E-5FN256C	188	1.2V	-5	fpBGA	256	COM	19.7K

Industrial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3C-3QN208I	136	1.8/2.5/3.3V	-3	PQFP	208	IND	3.1K
LFXP3C-4QN208I	136	1.8/2.5/3.3V	-4	PQFP	208	IND	3.1K
LFXP3C-3TN144I	100	1.8/2.5/3.3V	-3	TQFP	144	IND	3.1K
LFXP3C-4TN144I	100	1.8/2.5/3.3V	-4	TQFP	144	IND	3.1K
LFXP3C-3TN100I	62	1.8/2.5/3.3V	-3	TQFP	100	IND	3.1K
LFXP3C-4TN100I	62	1.8/2.5/3.3V	-4	TQFP	100	IND	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6C-3FN256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	5.8K
LFXP6C-4FN256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	5.8K
LFXP6C-3QN208I	142	1.8/2.5/3.3V	-3	PQFP	208	IND	5.8K
LFXP6C-4QN208I	142	1.8/2.5/3.3V	-4	PQFP	208	IND	5.8K
LFXP6C-3TN144I	100	1.8/2.5/3.3V	-3	TQFP	144	IND	5.8K
LFXP6C-4TN144I	100	1.8/2.5/3.3V	-4	TQFP	144	IND	5.8K

LatticeXP Family Data Sheet
Revision History

November 2007 **Data Sheet DS1001**

Revision History

Date	Version	Section	Change Summary
February 2005	01.0	—	Initial release.
April 2005	01.1	Architecture	EBR memory support section updated with clarification.
May 2005	01.2	Introduction	Added TransFR Reconfiguration to Features section.
		Architecture	Added TransFR section.
June 2005	01.3	Pinout Information	Added pinout information for LFXP3, LFXP6, LFXP15 and LFXP20.
July 2005	02.0	Introduction	Updated XP6, XP15 and XP20 EBR SRAM Bits and Block numbers.
		Architecture	Updated Per Quadrant Primary Clock Selection figure.
			Added Typical I/O Behavior During Power-up section.
			Updated Device Configuration section under Configuration and Testing.
		DC and Switching Characteristics	Clarified Hot Socketing Specification
			Updated Supply Current (Standby) Table
			Updated Initialization Supply Current Table
			Added Programming and Erase Flash Supply Current table
			Added LVDS Emulation section. Updated LVDS25E Output Termination Example figure and LVDS25E DC Conditions table.
			Updated Differential LVPECL diagram and LVPECL DC Conditions table.
			Deleted 5V Tolerant Input Buffer section. Updated RSDS figure and RSDS DC Conditions table.
			Updated sysCONFIG Port Timing Specifications
			Updated JTAG Port Timing Specifications. Added Flash Download Time table.
		Pinout Information	Updated Signal Descriptions table.
			Updated Logic Signal Connections Dual Function column.
		Ordering Information	Added lead-free ordering part numbers.
July 2005	02.1	DC and Switching Characteristics	Clarification of Flash Programming Junction Temperature
August 2005	02.2	Introduction	Added Sleep Mode feature.
		Architecture	Added Sleep Mode section.
		DC and Switching Characteristics	Added Sleep Mode Supply Current Table
			Added Sleep Mode Timing section
		Pinout Information	Added SLEEPN and TOE signal names, descriptions and footnotes.
			Added SLEEPN and TOE to pinout information and footnotes.
			Added footnote 3 to Logic Signal Connections tables for clarification on emulated LVDS output.
September 2005	03.0	Architecture	Added clarification of PCI clamp.
			Added clarification to SLEEPN Pin Characteristics section.
		DC and Switching Characteristics	DC Characteristics, added footnote 4 for clarification. Updated Supply Current (Sleep Mode), Supply Current (Standby), Initialization Supply Current, and Programming and Erase Flash Supply Current typical numbers.